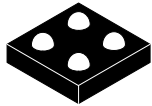
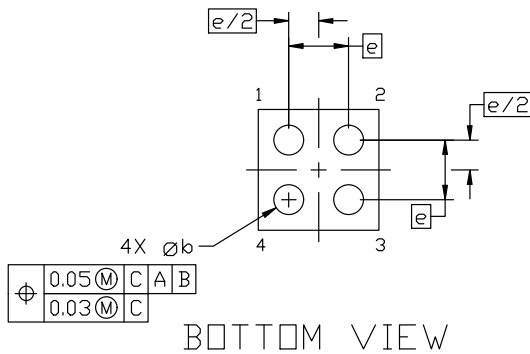
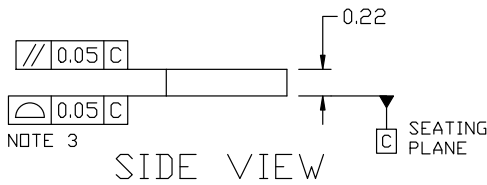
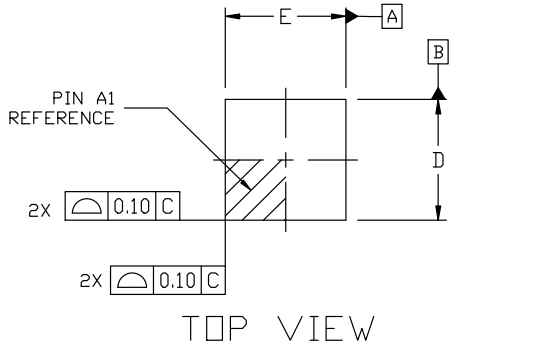


**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**



**WLCSP4, 1.01x1.01x0.22, 0.50P**  
**CASE 568AK**  
**ISSUE B**

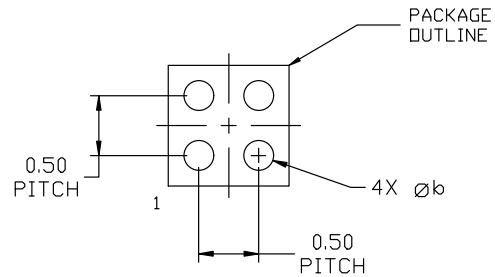
DATE 14 NOV 2023



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	0.22
b	0.22	0.25	0.28
D	0.99	1.01	0.11
E	0.99	1.01	0.11
e	0.50 BSC		



**RECOMMENDED MOUNTING FOOTPRINT**

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCES MANUAL, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>WLCSP4, 1.01x1.01x0.22, 0.50P</b>	<b>PAGE 1 OF 1</b>

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